Titles of Most Frequently Occurring Classifications of Patents Returne
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       From A Search of 09548826 on February 20, 2004

 7 714/718   (4 OR, 3 XR)
        Class   714 : ERROR DETECTION/CORRECTION AND FAULT
                          DETECTION/RECOVERY
        714/699   PULSE OR DATA ERROR HANDLING
        714/718   .Memory testing

 6 324/755   (1 OR, 5 XR)
        Class   324 : ELECTRICITY: MEASURING AND TESTING
        324/500   FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
                           ELECTRIC COMPONENTS
        324/537   .Of individual circuit component or element
        324/754   ..With probe elements
        324/755   ...Internal of or on support for device under
                           test (DUT)

 6 324/765   (3 OR, 3 XR)
        Class   324 : ELECTRICITY: MEASURING AND TESTING
        324/500   FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
                           ELECTRIC COMPONENTS
        324/537   .Of individual circuit component or element
        324/765   ..Test of semiconductor device

 6 365/201   (4 OR, 2 XR)
        Class   365 : STATIC INFORMATION STORAGE AND RETRIEVAL
        365/189.01   READ/WRITE CIRCUIT
        365/201   .Testing

 4 257/203   (1 OR, 3 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/202   GATE ARRAYS
        257/203   .With particular chip input/output means

 4 257/48   (3 OR, 1 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/48   TEST OR CALIBRATION STRUCTURE

 4 257/723   (0 OR, 4 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/688   .With large area flexible electrodes in press
                           contact with opposite sides of active semi
conductor chip
                        and surrounded by an insulating element, e
.g.,   ring

257/723   .For plural devices

    4   365/233   (0 OR, 4 XR)
            Class   365 : STATIC INFORMATION STORAGE AND RETRIEVAL
            365/230.01   ADDRESSING
            365/233   .Sync/clocking

    3   257/E21.525   (0 OR, 3 XR)
            Class   257 : ACTIVE SOLID-STATE DEVICES
            257/E21.515   .....Involving use of mechanical auxiliary par
t
                            without use of alloying or soldering pro
cess, e.g.,
                            pressure contacts (EPO)
            257/E21.521   .Testing or measuring during manufacture or
                            treatment or reliability measurement, i.e.
, testing of
                            parts followed by no processing which modi
fies parts as
                            such (EPO)
            257/E21.525   ..Procedures, i.e., sequence of activities
                            consisting of plurality of measurement and
    correction,
                            marking or sorting steps (EPO)

    3   257/E23.171   (0 OR, 3 XR)
            Class   257 : ACTIVE SOLID-STATE DEVICES
            257/E23.139   ...Liquid at normal operating temperature of
                            device (EPO)
            257/E23.141   .Arrangements for conducting electric current
                            within device in operation from one compo
nent to another,
                            interconnections, e.g., wires, lead frame
s (EPO)
            257/E23.169   ..Interconnection structure between plurality
                            of semiconductor chips being formed on or
in insulating
                            substrates (EPO)
            257/E23.171   ...Adaptable interconnections, e.g., for
                            engineering changes (EPO)

    3   257/E25.023   (0 OR, 3 XR)
            Class   257 : ACTIVE SOLID-STATE DEVICES
            257/E25.001   ASSEMBLIES CONSISTING OF PLURALITY OF
                            INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-
STATE DEVICES
(EPO)

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       257/E25.002   .All devices being of same type, e.g.,
                          assemblies of rectifier diodes (EPO)
       257/E25.022   ..Devices having separate containers (EPO)
       257/E25.023   ...Device consisting of plurality of
                          semiconductor or other solid-state devices
or components
                     formed in or on common substrate, e.g., int
egrated circuit

                     device (EPO)


   3   324/158.1     (0 OR,  3 XR)
          Class    324 :   ELECTRICITY:  MEASURING AND TESTING
          324/158.1       MISCELLANEOUS


   3   333/247       (3 OR,  0 XR)
          Class    333 :   WAVE TRANSMISSION LINES AND NETWORKS
          333/245          LONG LINE ELEMENTS AND COMPONENTS
          333/246          .Strip type
          333/247          ..Semiconductor mounts


   3   365/200       (2 OR,  1 XR)
          Class    365 :   STATIC INFORMATION STORAGE AND RETRIEVAL
          365/189.01       READ/WRITE CIRCUIT
          365/200          .Bad bit


   3   438/15        (2 OR,  1 XR)
          Class    438 :   SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

          438/14           WITH MEASURING OR TESTING
          438/15           .Packaging (e.g., with mounting, encapsulating
,
                     etc.) or treatment of packaged semiconducto
r

   3   714/724       (1 OR,  2 XR)
          Class    714 :   ERROR DETECTION/CORRECTION AND FAULT
                              DETECTION/RECOVERY
          714/699          PULSE OR DATA ERROR HANDLING
          714/724          .Digital logic testing

   2   257/678       (0 OR,  2 XR)
          Class    257 :   ACTIVE SOLID-STATE DEVICES
          257/678          HOUSING OR PACKAGE

   2   257/730       (0 OR,  2 XR)
          Class    257 :   ACTIVE SOLID-STATE DEVICES
          257/688          .With large area flexible electrodes in press
                              contact with opposite sides of active semi
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conductor chip
                    and surrounded by an insulating element, e
.g., ring
        257/730   .Outside periphery of package having specified
                        shape or configuration

  2 257/777   (0 OR, 2 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/734   COMBINED WITH ELECTRICAL CONTACT OR LEAD
        257/777   .Chip mounted on chip

  2 257/778   (1 OR, 1 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/734   COMBINED WITH ELECTRICAL CONTACT OR LEAD
        257/778   .Flip chip

  2 257/E21.512   (0 OR, 2 XR)
        Class   257 : ACTIVE SOLID-STATE DEVICES
        257/E21.001   PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE

                        OR TREATMENT OF SEMICONDUCTOR OR SOL
ID-STATE DEVICES
OR OF
                        PARTS THEREOF (EPO)
        257/E21.002   .Manufacture or treatment of semiconductor
                        device (EPO)
        257/E21.04   ..Device having at least one potential-jump
                        barrier or surface barrier, e.g., PN j
unction,
depletion
                        layer, carrier concentration layer (EP
O)
        257/E21.499   ...Assembling semiconductor devices, e.g.,
                        packaging , including mounting, encapsu
lating, or
treatment
                        of packaged semiconductor (EPO)
        257/E21.506   ....Attaching or detaching leads or other
                        conductive members, to be used for carry
ing current to
or
                        from device in operation (EPO)
        257/E21.509   .....Involving soldering or alloying process,
                        e.g., soldering wires (EPO)
        257/E21.511   ......Mounting on insulating member provided
                        with metallic leads, e.g., flip-chip mount
ing, conductive
                        die mounting (EPO)

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257/E21.512   ....Right-up bonding (EPO)

2 257/E23.004   (0 OR, 2 XR)
       Class   257 : ACTIVE SOLID-STATE DEVICES
       257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEVICE
S (EPO)
       257/E23.003   .Mountings, e.g., nondetachable insulating
                         substrates (EPO)
       257/E23.004   ..Characterized by shape (EPO)

2 257/E23.069   (0 OR, 2 XR)
       Class   257 : ACTIVE SOLID-STATE DEVICES
       257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEV
ICES (EPO)
       257/E23.01   .Arrangements for conducting electric current
                         to or from solid-state body in operatio
n, e.g., leads,
                         terminal arrangements (EPO)
       257/E23.023   ..Consisting of soldered or bonded
                         constructions (EPO)
       257/E23.06   ...Leads, i.e., metallizations or lead frames
                         on insulating substrates, e.g., chip carr
iers (EPO)
       257/E23.068   ....Additional leads joined to metallizations
                         on insulating substrate, e.g., pins, bumps
, wires, flat
                         leads (EPO)
       257/E23.069   .....Spherical bumps on substrate for external
                         connection, e.g., ball grid arrays (BGA) (E
PO)

2 257/E23.07   (0 OR, 2 XR)
       Class   257 : ACTIVE SOLID-STATE DEVICES
       257/E23.001   PACKAGING, INTERCONNECTS, AND MARKINGS FOR
                         SEMICONDUCTOR OR OTHER SOLID-STATE DEVI
CES (EPO)
       257/E23.01   .Arrangements for conducting electric current
                         to or from solid-state body in operation
, e.g., leads,
                         terminal arrangements (EPO)
       257/E23.023   ..Consisting of soldered or bonded
                         constructions (EPO)
       257/E23.06   ...Leads, i.e., metallizations or lead frames
                         on insulating substrates, e.g., chip carri
ers (EPO)
       257/E23.07   ....Geometry or layout (EPO)

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2  324/754        (0 OR, 2 XR)
       Class   324 :  ELECTRICITY:  MEASURING AND TESTING
       324/500          FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
                            ELECTRIC COMPONENTS
       324/537          .Of individual circuit component or element
       324/754          ..With probe elements

2  324/758        (0 OR, 2 XR)
       Class   324 :  ELECTRICITY:  MEASURING AND TESTING
       324/500          FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
                            ELECTRIC COMPONENTS
       324/537          .Of individual circuit component or element
       324/754          ..With probe elements
       324/758          ...Probe alignment or positioning

2  333/33          (0 OR, 2 XR)
       Class   333 :  WAVE TRANSMISSION LINES AND NETWORKS
       333/24R          COUPLING NETWORKS
       333/32           .With impedance matching
       333/33           ..Having long line elements

2  361/684         (0 OR, 2 XR)
       Class   361 :  ELECTRICITY:  ELECTRICAL SYSTEMS AND DEVICES

       361/600          HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
                            ELECTRICAL COMPONENTS
       361/679          .For electronic systems and devices
       361/683          ..Computer related support
       361/684          ...Memory unit support

2  361/783         (0 OR, 2 XR)
       Class   361 :  ELECTRICITY:  ELECTRICAL SYSTEMS AND DEVICES

       361/600          HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE
                            ELECTRICAL COMPONENTS
       361/679          .For electronic systems and devices
       361/748          ..Printed circuit board
       361/760          ...Connection of components to board
       361/783          ....Having semiconductive device

2  365/230.03      (0 OR, 2 XR)
       Class   365 :  STATIC INFORMATION STORAGE AND RETRIEVAL
       365/230.01       ADDRESSING
       365/230.03       .Plural blocks or banks

2  713/2           (2 OR, 0 XR)
       Class   713 :  ELECTRICAL COMPUTERS AND DIGITAL PROCESSING
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SYSTEMS: SUPPORT
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          713/1         DIGITAL DATA PROCESSING SYSTEM INITIALIZATION
                            OR CONFIGURATION (E.G., INITIALIZING, SET
UP,
                            CONFIGURATION, OR RESETTING)
          713/2         .Loading initialization program (e.g., booting
,
                            rebooting, warm booting, remote booting, BI
OS, initial
                            program load (IPL), bootstrapping)

    2   714/25          (0 OR, 2 XR)
          Class    714 :  ERROR DETECTION/CORRECTION AND FAULT
                            DETECTION/RECOVERY
          714/100         DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING

          714/1           .Reliability and availability
          714/25          ..Fault locating (i.e., diagnosis or testing)


    2   714/44          (1 OR, 1 XR)
          Class    714 :  ERROR DETECTION/CORRECTION AND FAULT
                            DETECTION/RECOVERY
          714/100         DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING

          714/1           .Reliability and availability
          714/25          ..Fault locating (i.e., diagnosis or testing)

          714/40          ...Component dependent technique
          714/44          ....Peripheral device component fault

    2   714/46          (1 OR, 1 XR)
          Class    714 :  ERROR DETECTION/CORRECTION AND FAULT
                            DETECTION/RECOVERY
          714/100         DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING

          714/1           .Reliability and availability
          714/25          ..Fault locating (i.e., diagnosis or testing)

          714/46          ...Operator interface for diagnosing or testin
g


    2   714/47          (0 OR, 2 XR)
          Class    714 :  ERROR DETECTION/CORRECTION AND FAULT
                            DETECTION/RECOVERY
          714/100         DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING
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       714/1            .Reliability and availability
       714/47           ..Performance monitoring for fault avoidance

  2  714/732         (1 OR, 1 XR)
       Class     714 :  ERROR DETECTION/CORRECTION AND FAULT
                           DETECTION/RECOVERY
       714/699          PULSE OR DATA ERROR HANDLING
       714/724          .Digital logic testing
       714/732          ..Signature analysis

  2  714/733         (1 OR, 1 XR)
       Class     714 :  ERROR DETECTION/CORRECTION AND FAULT
                           DETECTION/RECOVERY
       714/699          PULSE OR DATA ERROR HANDLING
       714/724          .Digital logic testing
       714/733          ..Built-in testing circuit (BILBO)
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PLUS Search Results for S/N 09548826, Searched February 20, 2004

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ch
system for U.S. Patents from 1971 to the present. PLUS is a
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RE36325
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5612657
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Most Frequently Occurring Classifications of Patents Returned
From A Search of 09548826 on February 20, 2004

Original Classifications
    4   365/201
    4   714/718
    3   257/48
    3   324/765
    3   333/247
    2   365/200
    2   438/15
    2   713/2

Cross-Reference Classifications
    5   324/755
    4   257/723
    4   365/233
    3   257/203
    3   257/E21.525
    3   257/E23.171
    3   257/E25.023
    3   324/158.1
    3   324/765
    3   714/718
    2   257/678
    2   257/730
    2   257/777
    2   257/E21.512
    2   257/E23.004
    2   257/E23.069
    2   257/E23.07
    2   324/754
    2   324/758
    2   333/33
    2   361/684
    2   361/783
    2   365/201
    2   365/230.03
    2   714/25
    2   714/47
    2   714/724

Combined Classifications
    7   714/718
    6   324/755
    6   324/765
    6   365/201

4	257/203
4	257/48
4	257/723
4	365/233
3	257/E21.525
3	257/E23.171
3	257/E25.023
3	324/158.1
3	333/247
3	365/200
3	438/15
3	714/724
2	257/678
2	257/730
2	257/777
2	257/778
2	257/E21.512
2	257/E23.004
2	257/E23.069
2	257/E23.07
2	324/754
2	324/758
2	333/33
2	361/684
2	361/783
2	365/230.03
2	713/2
2	714/25
2	714/44
2	714/46
2	714/47
2	714/732
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